

Patent Abstracts of Japan

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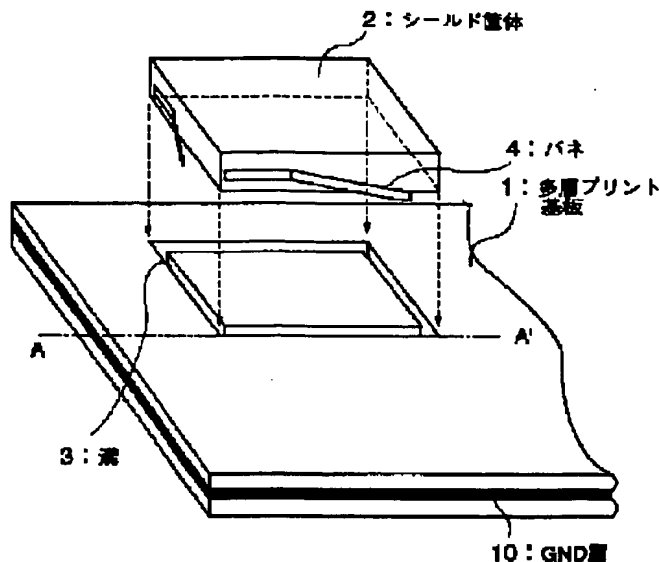
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TITLE : SHIELDING STRUCTURE FOR  
MULTILAYERED PRINTED BOARD



ABSTRACT : PROBLEM TO BE SOLVED: To improve the isolation of a printed wiring board from the outside so as to improve the shielding property of a shielding structure by forming a groove which reaches a GND layer and in which the entire end section of a shielding enclosure can be put on the wiring board and laying an elastic conductor on the bottom of the groove, and then, putting the entire end section of the enclosure in the groove.

SOLUTION: A groove 3 in which the entire square frame at the end section of a shielding enclosure 2 can be put is formed on the part of a printed board 1 to be shielded so that the groove 3 can reach a GND layer 10. Then an elastic conductor 5 is laid on the bottom of the groove 3 and the enclosure 2 is mounted on the board 1 by putting the end section of the enclosure 2 in the groove 3. Therefore, a tight shielding structure can be formed, because the GND layer 10 is firmly, tightly, and electrically connected to the end section of the enclosure 2 through the conductor 5. Since the enclosure 2 is mounted on the board 1 by putting the end section of the enclosure 2 in the groove 3, the enclosure 2 can be easily mounted on the board 1 without requiring soldering, can be easily positioned, and the enclosure 2 can be mounted on the board 1 without positional deviation.

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